

Exhibit 1 ID Label Location

Uppgjord (även faktaansvarig om annan) – Prepared (also subject responsible if other)	Nr - No.	Rev
Magnus Sneitz	10201– SPB209A Marking Instruction	E
Dokansv/Godk - Doc respons/Approved Kontr - PB	Datum - Date	File
	2016-12-21	

SPB209A Module Marking Instruction

Revision History

Revision	Revision date	Description
PA1	2015-02-19	First Draft
A	2016-02-24	First formal release. <ul style="list-style-type: none">- Updated marking orientation in section 2.1 and 2.2- Added 1000pcs reel amount under section 3
B	2016-06-22	Marking instruction changed for LTE filter version
C	2016-08-11	Marking instruction changed for FCC approval
D	2016-12-15	Marking instruction changed for ISED approval
E	2016-12-21	Separate instructions for SPB209A and SPB209A-BNM

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1 Scope

This document defines the re-marking and re-packs of the SPB209A module and describes the procedure.

2 Marking

2.1 Mechanical outline 41pin Package



Figure 2.1: Mechanical drawing, equivalent to a 41 pin Quad Flat No-Lead (QFN) package.

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2.2 Mechanical outline 38pin Package

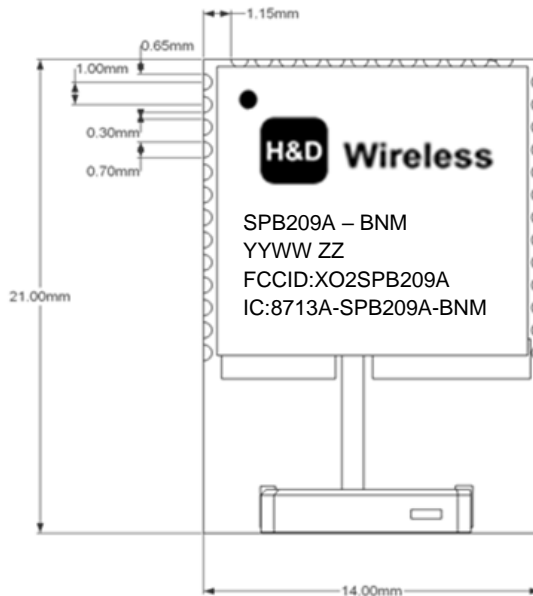


Figure 2.2: Mechanical drawing, equivalent to a 38 pin Quad Flat No-Lead (QFN) package

2.3 Marking SPB209A package

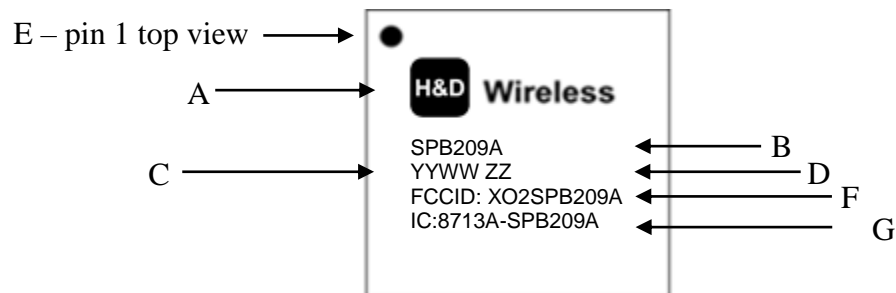


Figure 2.3: SPB209A package marking.

Ref	Marking	Description
A	H&D Wireless	Company Logo Square around H&D is 2mm x 2mm
B	SPB209A - RNM	Product name / HVIN – Product version (Font: Arial)
C	YYWW	Production date. YY= year, WW=week (Font: Arial)
D	ZZ	Production lot, start on 01, (Font: Arial)
E	Dot	Defines pin 1 (Top view)
F	FCCID: XO2SPB209A	FCC approval number
G	IC:8713A-SPB209A	ISED approval number

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Table 1: QFN package marking description

2.4 Marking SPB209A-BNM package

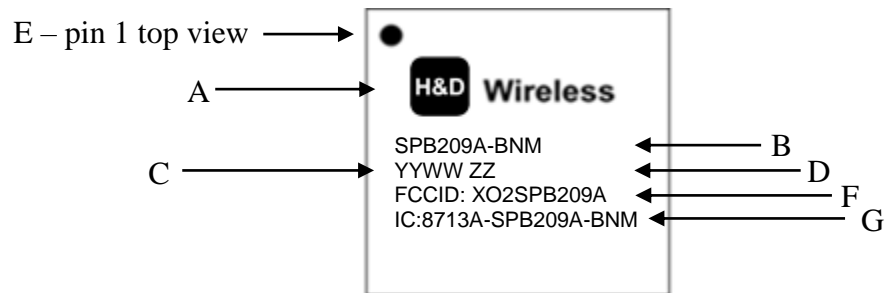


Figure 2.4: SPB209A package marking.

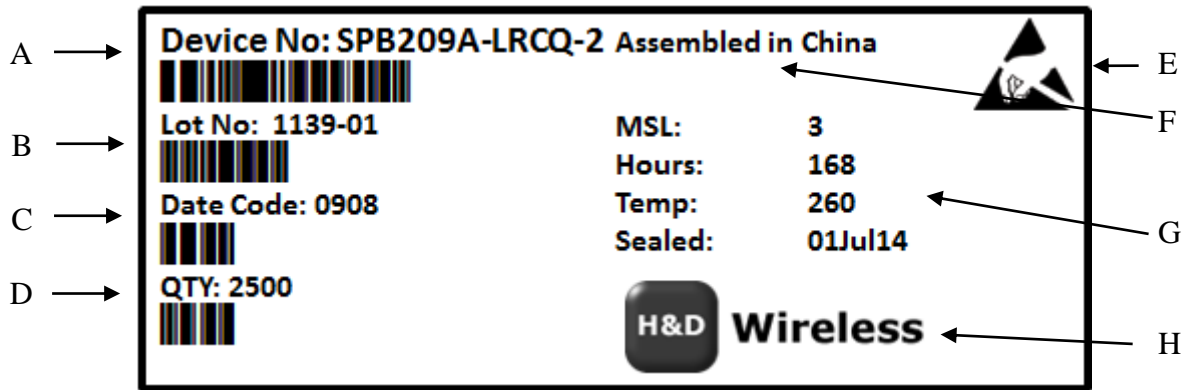
Ref	Marking	Description
A	H&D Wireless	Company Logo Square around H&D is 2mm x 2mm
B	SPB209A - BNM	Product name / HVIN – Product version (Font: Arial)
C	YYWW	Production date. YY= year, WW=week (Font: Arial)
D	ZZ	Production lot, start on 01, (Font: Arial)
E	Dot	Defines pin 1 (Top view)
F	FCCID: XO2SPB209A	FCC approval number
G	IC:8713A-SPB209A-BNM	ISED approval number

Table 2: SPB209A-BNM package marking description

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2.5 Labels

The labels for reel, bag and box are identical.



Ref	Item	Value
Size	101.5 x 63.5mm	
A	Device No in Text and Bar Code	SPB209A
B	Lot ID in Text and Bar Code	In-Tech lot number
C	Date code in Text and Bar Code	YYWW-NN (year week - serial)
D	Quantity in Text and Bar Code	
E	ESD Caution	
F	Assembly location	Optional
G	MSL data	Class, bake time, Temp, Seal date
H	Logo	H&D Wireless logo

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3 Procedure

All handling, baking, packing and shipping of ESD and moisture sensitive components is according to IPC/JEDEC J-STD-033 (MSL3)

- Mark inscription according to 2.3
- Baking according to MSL3
- Tape& reeling 500 pcs/reel, 1000 pcs/reel or 2500 pcs/reel according to EIA-481
- Packing MBB with desiccant pouches, HIC and labels according to the standard.
- Labels. Print and apply labels according to the pictures below.

